

UMF Equipment – Rapid Thermal Processor

AccuThermo AW410

The Rapid Thermal Process System is an instrument which heats wafers to high temperatures on a timescale of several minutes or less. Such rapid heating rates are attained by high intensity lamps process. RTP is used for a wide variety of applications in semiconductor manufacturing including ion implant activation, polysilicon annealing, dopant activation, thermal oxidation and metal reflow.

Features:

Substrate size: Up to 4" diameter

Temp. range: Room temp. to ~1150°C

• Ramp up rate: > 50°C /sec

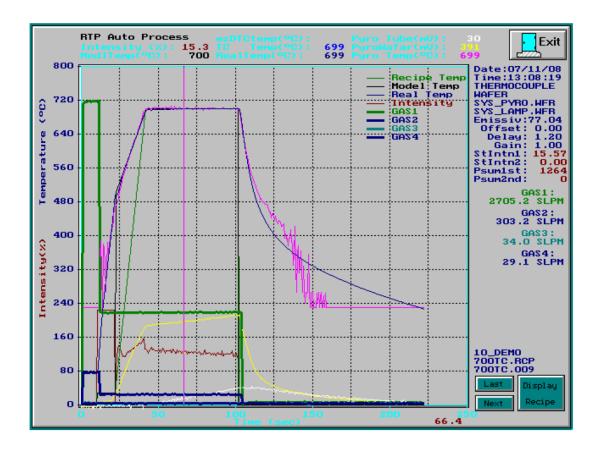
• Gas lines: N₂, O₂, Ar

• Temperature/ Time control: Temperature measuring precision ≤ ±2°C

Please refer to supplier information page: https://allwin21.com/ for further details of the system. For any inquiry, please contact Dr. Terence Wong (Tel: 3400 2075; Email: tai-lun.wong@polyu.edu.hk).



Rapid Thermal Processor



Process Monitor Screen